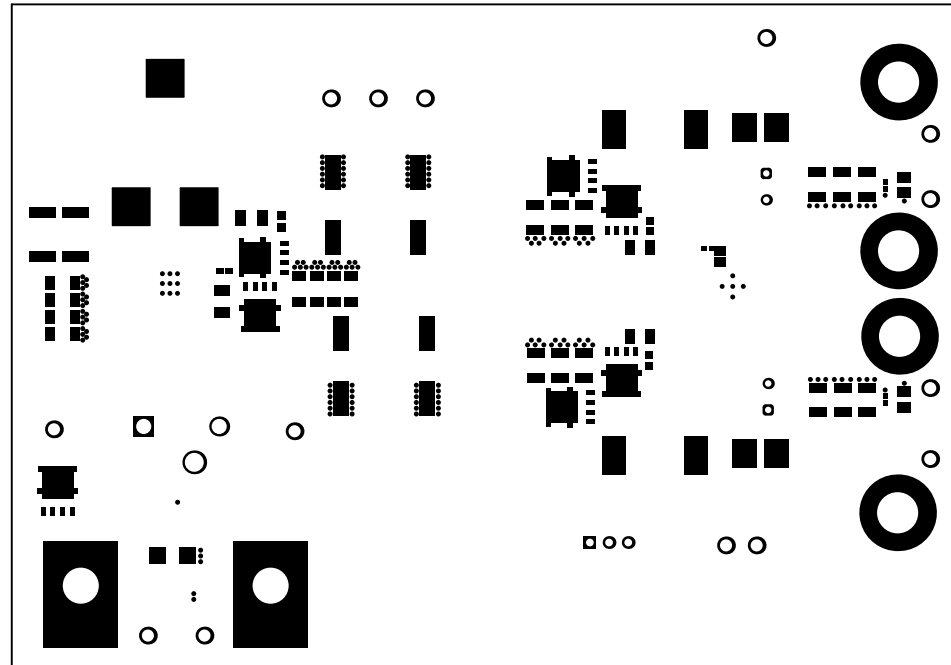
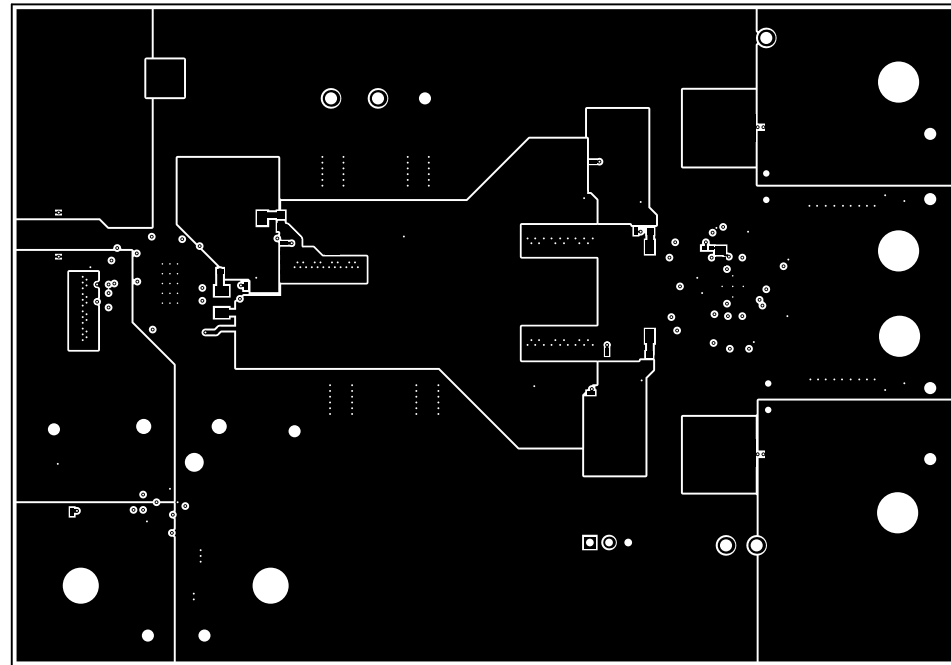


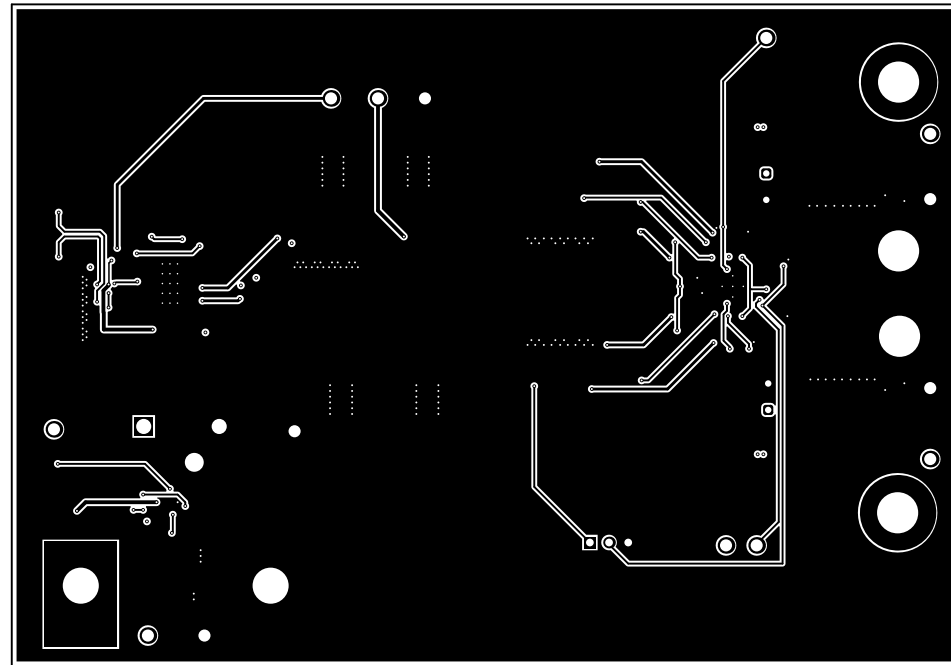
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Top Overlay	TID #: TIDA-01553		
PLOT NAME = Top Overlay	GENERATED : 12/19/2017 7:12:53 AM	TEXAS INSTRUMENTS	



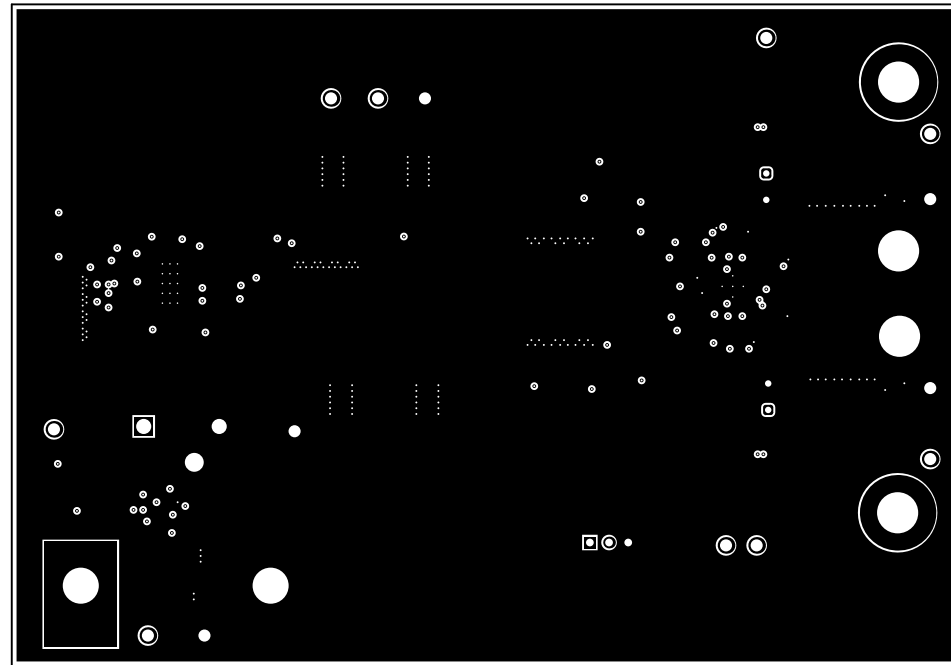
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Top Solder	TID #: TIDA-01553		
PLOT NAME = Top Solder Mask	GENERATED : 12/19/2017 7:12:54 AM	TEXAS INSTRUMENTS	



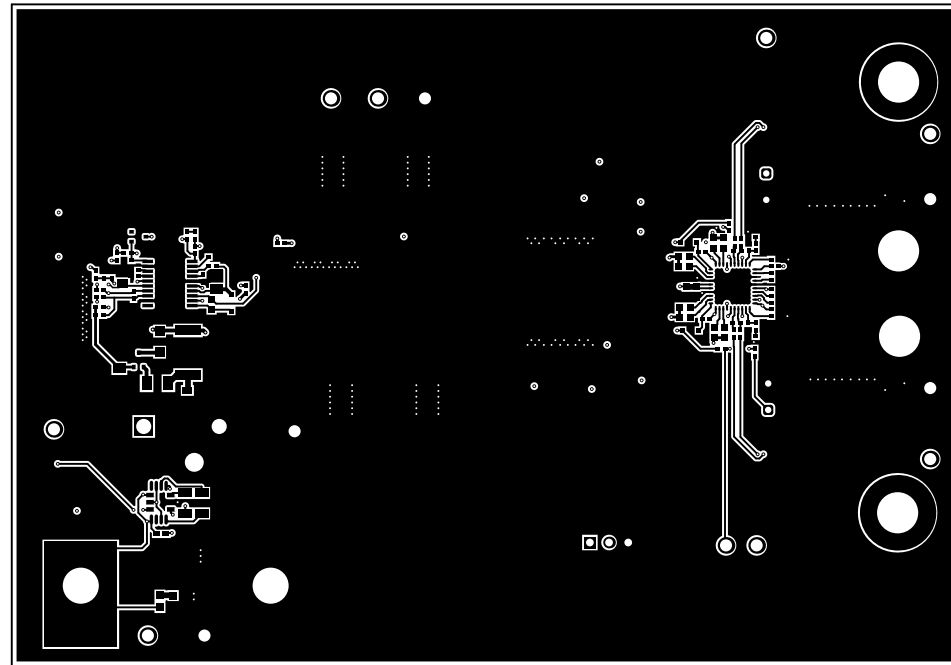
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Top Layer	TID #: TIDA-01553		
PLOT NAME = Top Layer	GENERATED : 12/19/2017 7:12:55 AM	TEXAS INSTRUMENTS	



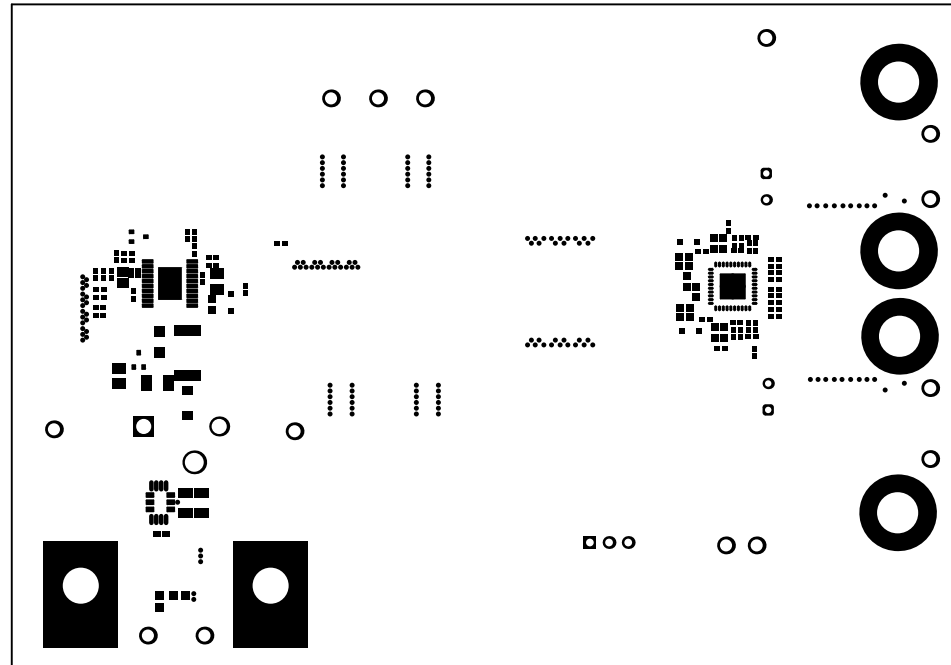
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME =	TID #: TIDA-01553		
PLOT NAME = Signal Layer 1	GENERATED : 12/19/2017 7:12:56 AM	TEXAS INSTRUMENTS	



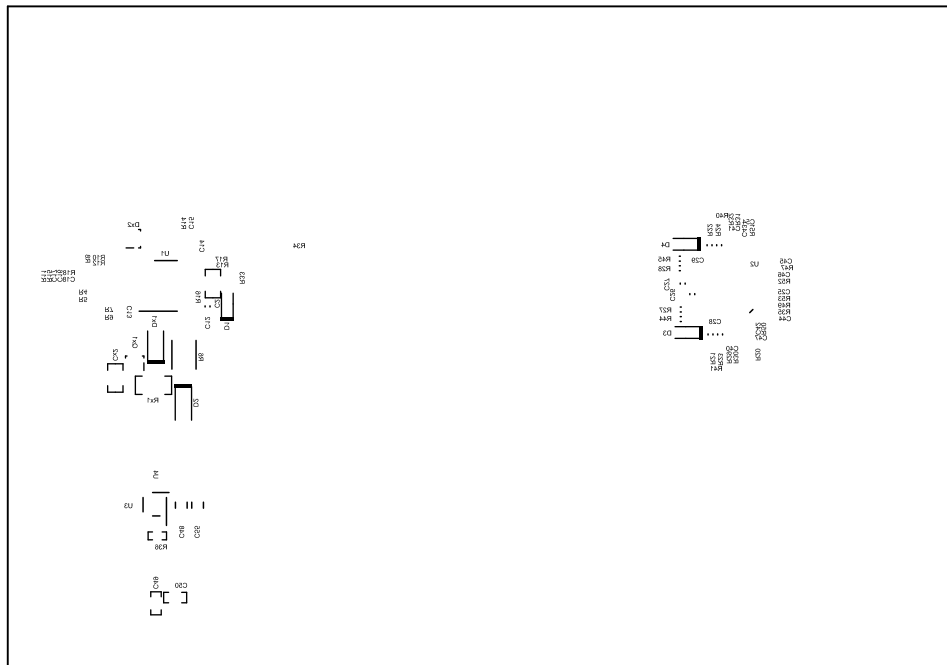
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME =	TID #: TIDA-01553		
PLOT NAME = Signal Layer 2	GENERATED : 12/19/2017 7:12:57 AM	TEXAS INSTRUMENTS	



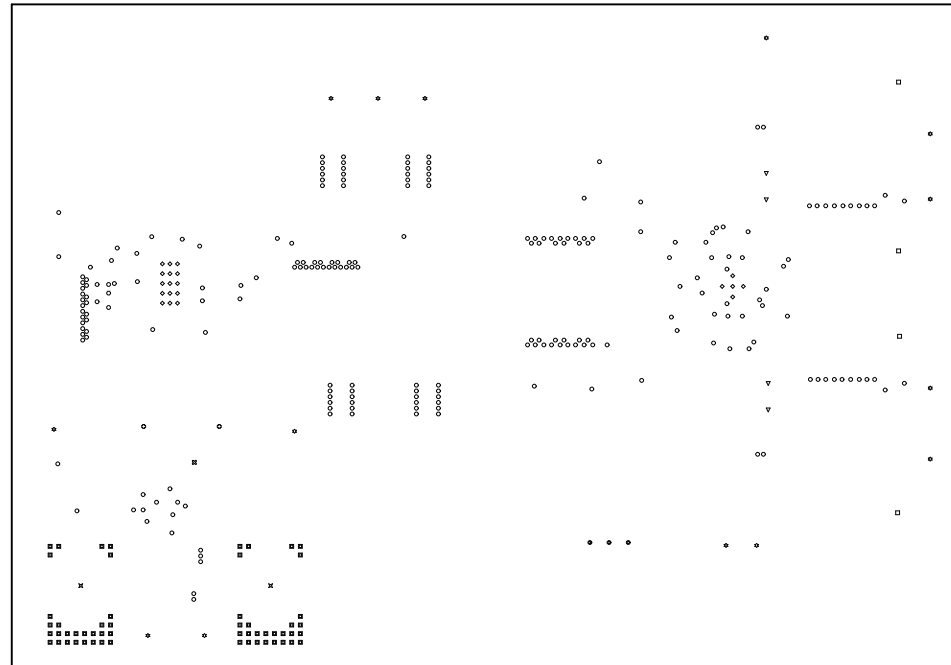
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Bottom Layer	TID #: TIDA-01553		
PLOT NAME = Bottom Layer	GENERATED : 12/19/2017 7:12:58 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Bottom Solder	TID #: TIDA-01553		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/19/2017 7:12:58 AM	TEXAS INSTRUMENTS	

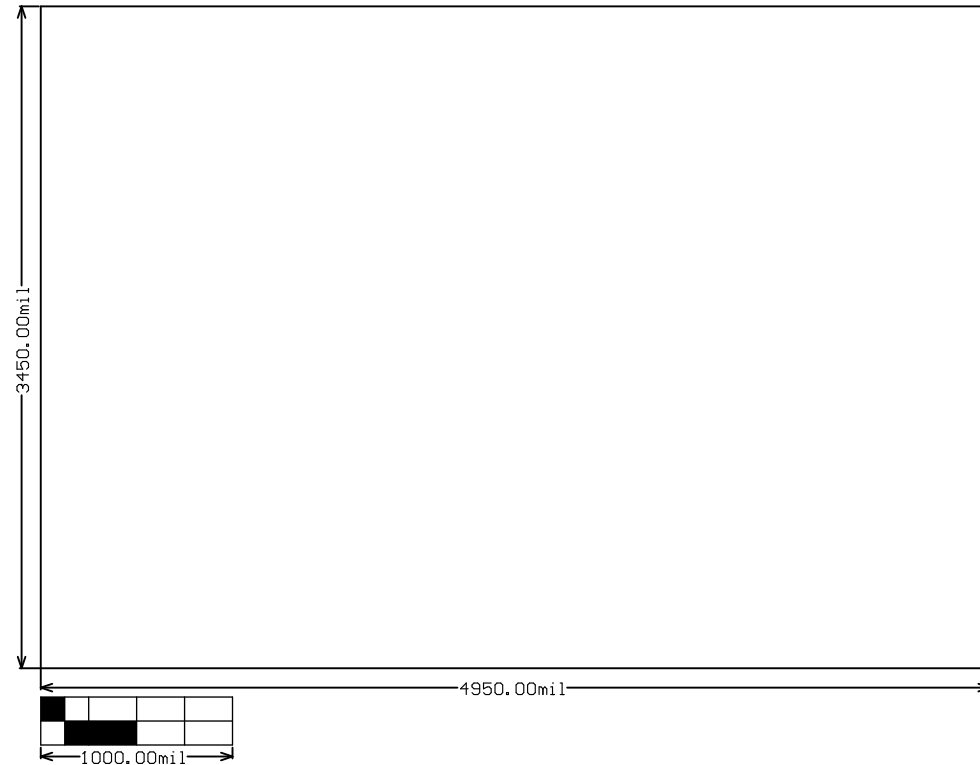


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Bottom Overlay	TID #: TIDA-01553		
PLOT NAME = Bottom Overlay	GENERATED : 12/19/2017 7:12:59 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	20	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	225	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
■	56	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	3	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	14	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	1	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
⊡	2	188.00mil (4.775mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	214.57mil (5.450mm)	PTH	Round	Top Layer - Bottom Layer	
	331 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = Drill Drawing	TID #: TIDA-01553		
PLOT NAME = Drill Drawing	GENERATED : 12/19/2017 7:13:00 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01553	REV: B	SUN REV: 3501
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01553		
PLOT NAME = Board Dimensions	GENERATED : 12/19/2017 7:13:02 AM	TEXAS INSTRUMENTS	

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